Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type $(\pi$ -MOSII 5)

2SK1489

Chopper Regulator Applications

• Low drain–source ON resistance : RDS (ON) = 0.8Ω (typ.) • High forward transfer admittance : $|Y_{fs}| = 6.0 S$ (typ.) • Low leakage current : IDSS = $300 \mu A$ (max) (VDS = 800 V)

• Enhancement mode $: V_{th} = 1.5 \sim 3.5 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Absolute Maximum Ratings (Ta = 25°C)

Characteris	stics	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	1000	V	
Drain-gate voltage (R	_{GS} = 20 kΩ)	V_{DGR}	1000	V	
Gate-source voltage		V_{GSS}	±30	V	
Drain current	DC (Note 1)	I_{D}	12	Α	
Diain current	Pulse (Note 1)	I _{DP}	36		
Drain power dissipation	n (Tc = 25°C)	P_{D}	200	W	
Channel temperature		T _{ch}	150	°C	
Storage temperature ra	ange	T _{stg}	-55~150	°C	

2-21F1B

Weight: 9.75 g (typ.)

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Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	0.625	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	35.7	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

This transistor is an electrostatic-sensitive device.

Please handle with caution.



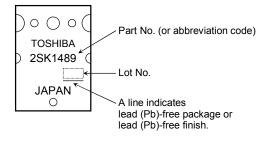
Electrical Characteristics (Ta = 25°C)

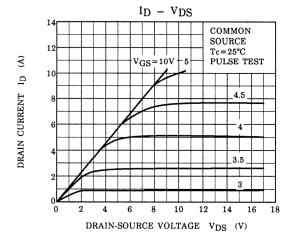
Charac	eteristics	Symbol	Test Condition	Min	Тур.	Max	Unit	
Gate leakage cu	rrent	I _{GSS}	V _{GS} = ±25 V, V _{DS} = 0 V	_	_	±100	nA	
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 800 V, V _{GS} = 0 V	1	_	300	μA	
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	1000	_	-	V	
Gate threshold v	voltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	1.5	_	3.5	V	
Drain-source Ol	N resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 6 A		0.8	1.0	Ω	
Forward transfer	admittance	Y _{fs}	V _{DS} = 20 V, I _D = 6 A	4.0	6.0	_	S	
Input capacitano	:e	C _{iss}		_	2000	_	pF	
Reverse transfer	r capacitance	C _{rss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	1	220	_		
Output capacita	nce	Coss		1	360	-		
Switching time	Rise time	t _r	V_{GS} V_{OV} V_{DD} V_{DD} V_{DD}	_	100	_	ns	
	Turn-on time	t _{on}		_	140	_		
	Fall time	t _f		_	150	_		
	Turn-off time	t _{off}	Duty $\leq 1\%$, $t_{\mathbf{W}} = 10 \mu \text{s}$	_	500	_		
Total gate charg plus gate–drain)		Qg			110	_		
Gate-source charge		Q _{gs}	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 12 \text{ A}$		50	_	nC	
Gate-drain ("miller") charge		Q_{gd}			60	_		

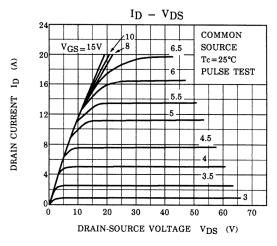
Source-Drain Ratings and Characteristics (Ta = 25°C)

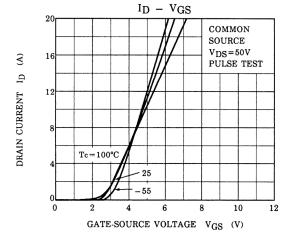
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	12	Α
Pulse drain reverse current (Note 1)	I _{DRP}		_	_	36	Α
Forward voltage (diode)	V_{DSF}	I _{DR} = 12 A, V _{GS} = 0 V	1		-1.6	V

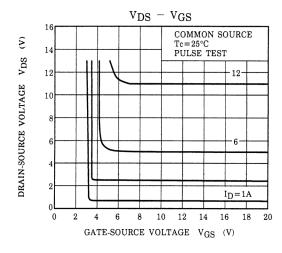
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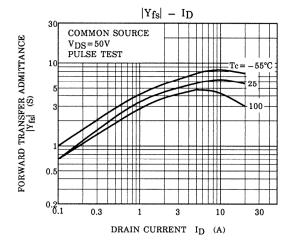


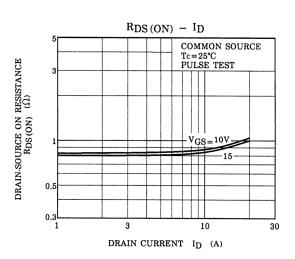


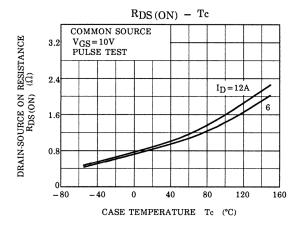


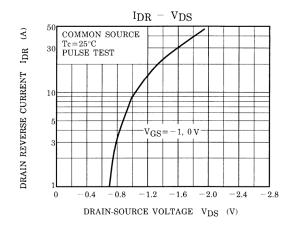


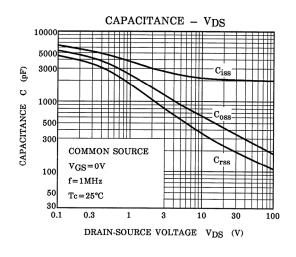


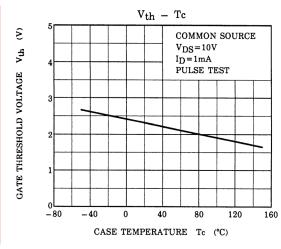


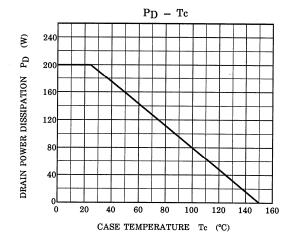


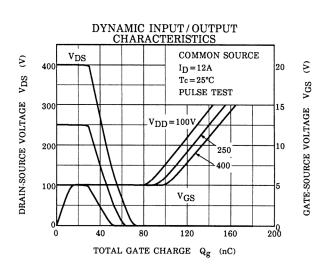




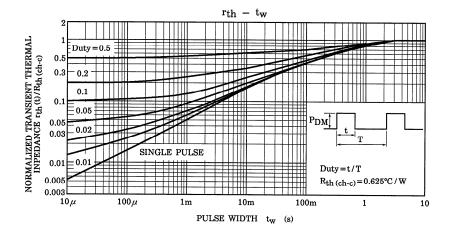


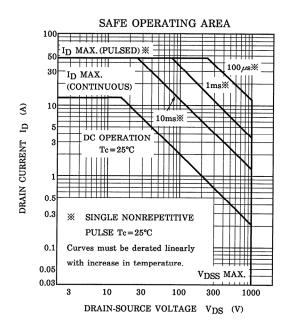






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